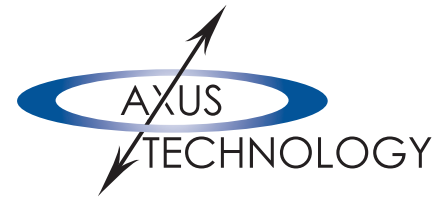


IPEC 776 CMP Tool

Automated Dry-in/Dry-out



Your source for leading-edge surface processing solutions



The IPEC 776 is the most widely installed dry-in, dry-out orbital CMP platform available. The 776 includes a fully automated wafer handling system with a Spray Station Assembly used to remove slurry particulates and keep the wafers wet throughout the process.

STD FEATURES

- Four wafer planarizers (polishing modules) with mini environment
- Integrated double side PVA cleaner with dual brush station and SRD
- Three cassette tilter load/unload station
- Post-CMP buff station
- High speed polish drive (0-600 RPM)
- Closed loop delta P control; provides operational feedback
- Endpoint detection system
- Robot R1/R2/R3 equipped
- Stainless steel polish bells
- Pad conditioners; one for each two polish modules
- SECS/GEM capable
- Upgraded 500MHz Pentium

AVAIL OPTIONS

- Slurry distribution interface upgrade with multiplexer to signal low slurry
- CPU upgrade to 1 GHz CPU plus memory upgrade
- Advanced pad motion control; improves wafer coverage during polishing

DIMENSIONS		FACILITIES	
mm	1981W x 3226D x 2413H	Power	208 VAC, 50-60 Hz
Inches	78W x 127D x 95H	DI Water	Min. 40psi / 2gpm